



DEPARTMENTS

	AEI NEWS	08
	IN VIEW THIS MONTH	10
	BUSINESS STRATEGY	55
	COMPANY ON THE MOVE	56
	PRODUCT NEWS	64

ASIA ELECTRONICS INDUSTRY (ISSN 1342-422X) is published monthly by Dempa Publications, Inc., 1-11-15 Higashi Gotanda, Shinagawa-ku, Tokyo 141-8715, Japan Tel: +81-3-3445-6111 Fax: +81-3-3445-6890. Editorial e-mail: may@dempa.co.jp;

Subscription e-mail: circulationmanila@dempa.co.jp. The magazine is distributed free to qualified subscribers in ASEAN countries (Thailand, Indonesia, The Philippines, Malaysia, Singapore, Brunei, Vietnam, Myanmar, Cambodia and Laos), as well as Korea, Taiwan and Hong Kong.

Paid air mail subscription is available to non-qualified subscribers in the Asian and Pacific regions for US\$150 per year and US\$260 for two years. For other areas, air mail subscription fees are US\$160 per year and US\$280 for two years. Paid subscription is accepted at <https://www.dempa.co.jp/en/pdfs/orderform.pdf>

Send address corrections to Dempa Publications, Inc., c/o Quantum Solutions (HK) Ltd. Unit 3-6, G/F Pacific Trade Centre, 2 Kai Hing Road, Kowloon Bay, Kowloon, Hong Kong

TAIWAN: International Dempa Trade Co. Ltd., 7F, No. 34, Sec. 1, Nanjing East Road., Taipei, Taiwan 104 Tel: +886-2-2563 4595 Fax: +886-2-2567-5559 **KOREA:** Dempa Publications, Room 1019, Punglim VIP Tel, 404, Gongdeuk-dong, Mapo, Seoul, Korea 04144, Tel: +82-2-714-2983 Fax: +82-2-714-2984 **PHILIPPINES:** Dempa Publications, Inc. - Regional Headquarters, Herrera Tower, Room 2510, 98 V.A. Rufino Street, Salcedo Village, Makati City, Philippines, Tel: +63-2-845-0906 Fax: +63-2-845-1829

President & Publisher: Tsutomu Hirayama
Copyright © 2019 by Dempa Publications, Inc.

All rights reserved. The contents of this magazine may not be reproduced in whole or in part without the prior permission of the copyright owner. Printed in China.

NEPCON ASIA 2019

FUJI	13
Tokyo Weld	16
Japan Unix	18
JUKI	20
Yamaha Motor	24
Panasonic	27

SPECIAL REPORT

Electronic Circuit Boards Technologies Deal With Heat	30
Automotives Heat up Demand for Capacitors	31

TECH FOCUS

Study Fuses New Components, Yields Next-Generation Memory	35
---	----

COMPONENT MATERIALS

SMTs: IN REVIEW

IN THE KNOW

Mass Production Changes Course of Mounting Technologies	42
---	----

TECHNOLOGY HIGHLIGHT

New Process Yields Low-Temperature Diamond, Silicon Bonding	44
Simulation Model Predicts Energy Loss, Noise of Power Devices	46

PRODUCT HIGHLIGHT

iCAP Tackles Main Challenges of Large-Scale IoT Deployment	47
MEMS Ultrasonic ToF Sensors Offer Millimeter-Range Noise Precision	48
Power Supply IC With BIST Supports Automotive Safety	49

SHOW REPORT

SID 2019	50
----------	----

INDUSTRY REPORT

Advanced Parts to Suit up Next-Generation Robots	52
--	----

ZOOM-IN

COMPANY PROFILE

Cognitive Systems' WiFi Motion Technology Disrupts Home Security Market	57
Etron Puts 3D Depth Map Sensor at Fore of AI Ecosystem Push	58

SHOW PREVIEW

Taitronics 2019	60
-----------------	----